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TD041S485S DFN package isolated RS485 Transceiver

Features

- · Ultra-small, ultra-thin, chip scale DFN package
- · Compliant with TIA/EIA-485-A standard
- I/O power supply range supports 3.3V and 5V microprocessors
- · High isolation to 3750Vrms
- Bus-Pin ESD protection up to 15kV(HBM)
- Baud rate up to 20Mbps
- > 25kV/µs CMTI
- Low communication delay
- 1/8 unit load—up to 256 nodes on a bus
- Bus fail-safe
- Bus driver short circuit protection
- Meet AEC-Q100 Standards
- Meet EN62368 Standards
- Moisture Sensitivity Level (MSL) 3

Applications

- Industrial Automation
- Building Automation
- Smart Electricity Meter
- Remote Signal Interaction, Transmission

Package





Functional Description

TD041S485S is a half-duplex enhanced transceiver designed for RS-485 data bus networks.which is fully compliant with TIA/EIA-485-A standard and is suitable for data transmission of up to 20 Mbps. Their logic side supports 3.3V and 5V logic level conversion. Receivers have an exceptionally high input impedance which places only 1/8 of the standard load on a shared bus and up to 256 transceivers.

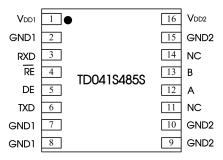
TD041S485S reliability design of A, B pin is emphasized, including driver output over current protection and enhanced ESD design. The ESD protection level of A,B pin can be up to 15KV (Human Body Model).

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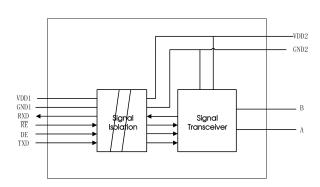
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Pin Connection



Note: All GND1 pins are internally connected; All GND2 pins are internally connected.

Internal Block Diagram



Function Table

Letter	Description
Н	High-Level
L	Low-Level
X	Unrelated
Z	High Impedance
NC	No Connection

Table 1. Driver Function Table

Power		In	put	Output		
Vdd1	V _{DD2}	DE	TXD	A	В	
On	On	Н	Н	Н	L	
On	On	Н	L	L	Н	
On	On	L	X	Z	Z	
On	Off	X	X	Z	Z	
Off	Off	L	L	Z	Z	
Off	Off	X	X	Z	Z	

Table 2. Receiver Function Table

Power		Input		Output
V _{DD1}	Vdd2	A-B (V)	RE	RxD
On	On	≥-0.01	L or NC	Н
On	On	≤-0.2	L or NC	L
On	On	-0.2 < A - B < -0.01	L or NC	Indeterminate
On	On	OPEN	L or NC	Н

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On	Off	X	L or NC	Н
Off	Off	X	L or NC	L

Pin Descriptions

Pin Number	Pin Name	Pin Functions
1	VDD1	Power Supply(Logic side)
2	GND1	Ground(Logic side)
3	RXD	Receiver Output Data
4	RE	Receiver Enable Input. When \overline{RE} is low, if $(A-B) \ge -10$ mV, then RxD = high. If $(A-B) \le -200$ mV, then RxD = low.
5	DE	Driver Enable Input. When DE is high, outputs are enabled. When DE is low, outputs are high impedance. Drive DE low and RE high to enter shutdown mode.
6	TXD	Driver Input
7	GND1	Ground(Logic side)
8	GND1	Ground(Logic side)
9	GND2	Ground (Bus Side)
10	GND2	Ground (Bus Side)
11	NC	No Connect
12	А	RS485 Bus A Line
13	В	RS485 Bus B Line
14	NC	No Connect
15	GND2	Ground (Bus Side)
16	VDD2	Power Supply (Bus Side)

Absolute Maximum Ratings

General test conditions: Free-air, normal operating temperature range (unless otherwise specified).

PARAMETERS	UNIT
V_{DD1}	−0.5 V to +7 V
V_{DD2}	−0.5 V to +6 V
Digital Input Voltage (DE, RE, TXD)	-0.3V to +6V
Digital Output Voltage (RxD)	-0.3V to +6V
Driver Output / Receiver input Voltage	-8 V to +13 V
Operating Temperature Range	-40°C to +105°C
Storage Temperature Range	−50°C to +125°C
Reflow Soldering Temperature	Peak temp. ≤260 °C, maximum duration ≤60s at 217 °C. Please also refer to IPC/JEDEC J-STD-020D.3.

Important: Exposure to Absolute Maximum Rated conditions for an extended period may severely affect the device reliability, and stress levels exceeding the "Absolute Maximum Ratings" may result in permanent damage.

Recommended Operating Conditions

Recommended Operating Conditions			Тур.	Max.	Unit
V_{DD1}	Logic Power Supply	2.375	3.3	5.5	
V_{DD2}	Bus Power Supply	4.5	5	5.5	
V _{IH}	High-level input voltage(TXD, DE, RE)	2		V _{DD1}	V
V _{IL}	Low-level input voltage(TXD, DE, RE)	0		0.8	
V_{ID}	Differential input voltage	-7		+12	
R _L	Differential output load resistance	54	60		Ω
	Signaling rate			20	Mbps

	PARAMETERS	COND	TIONS	Min.	Тур.	Max.	Unit
DRIVER							
157 1	Differential Driver Outrot	R _L = ∞,	Figure 9	3			V
V _{OD}	Differential Driver Output	R_L = 54 Ω (RS-485), Figure 9		1.5		5.5	V
Δ V _{OD}	Δ V _{OD} for Complementary Output States	R _L = 54 Ω	, Figure 9			0.2	V
V _{OC(SS)}	Common-Mode Output Voltage	Figu	re 10	1		3	V
$\Delta V_{\text{OC(SS)}}$	Δ V _{oc} for Complementary Output States	Figu	re 10			0.2	V
los	Output Short-Circuit Current	-7V≤V _C	_{l∪T} ≤12V		±110	±250	mA
V _{IH}	Input High Voltage	TXD, [DE. RE	2			V
V _{IL}	Input Low Voltage	TXD, [0.8	V
R _{TXD}	Internal TXD Pull up Resistor	,	,		9.1		kΩ
R _{DE} , R _{RE}	Internal DE, RE Pull down Resistor				9.1		kΩ
RECEIVE					1		
V _{IT(+)}	Positive Differential Input Threshold Voltage	-7 V ≤ VC	M ≤ +12 V			-10	mV
V _{IT(-)}	Negative Differential Input Threshold Voltage	-7 V ≤ VCM ≤ +12 V		-200			mV
V _{hys}	Hysteresis Voltage (V _{IT+} – V _{IT-})	-7 V ≤ VCM ≤ +12 V			20		mV
R _{ID}	Differential Input Resistance(A,B)	-7 V ≤ VC	M ≤ +12 V	96			kΩ
l ₁	Input Current (A, B)		V _{OUT} =12V		190	250	uA
		DE=0, RE=0	V _{OUT} = -7V	-200	-110		uA
V.	DVD Output Lligh Voltage	Ι _{ΟυΤ} = 20 μΑ, \	/ _A – V _B = 0.2 V	V _{DD1} - 0.1			V
V _{OH}	RXD Output High Voltage	I _{OUT} = 4 mA, V	$V_{A} - V_{B} = 0.2 \text{ V}$	V _{DD1} - 0.4	V _{DD1} - 0.2		V
Vol	RXD Output Low Voltage	$I_{OUT} = -20 \mu A$,	$V_A - V_B = 0.2 \text{ V}$			0.1	V
VOL	TOOD Output Low Voltage	$I_{OUT} = -4 \text{ mA}, V$	$V_A - V_B = 0.2 \text{ V}$			0.4	V
Supply an	d Protection						
I _{DD1}	Supply Current(Logic side)	$4.5 \text{ V} \le \text{V}_{\text{DD1}} \le 5.5 \text{ V}$	', No load, $\overline{RE} = 0 \text{ V}$			4.5	mA
.001	cappi, caironi(cogic ciac)	$3.0 \text{ V} \le \text{V}_{\text{DD1}} \le 3.6 \text{ V}$	', No load, $\overline{RE} = 0 \text{ V}$			3.5	mA
I _{DD2}	Supply Current(Bus side)	No load,	DE = 5 V			4.5	mA
-552		No load,	DE = 0 V			4.5	mA
	НВМ	A, B ar	d GND			±15	kV
ESD		Othe	r pins			±2	kV
	IEC/EN 61000-4-2 (Contact) Perf. Criteria B	A, B and GND				±4	kV
EFT	IEC61000-4-4: Perf. Criteria B	A, B and GND				±2	kV
Surge	IEC61000-4-5 : Perf. Criteria B	A, B and GND(Common Mode)			±2	kV
V _{I-O}	Isolation Test	Leakage cu	urrent <1mA.			3750	Vrms
Rı-o	Insulation Resistance	At 50	0VDC	1000			ΜΩ
C _{I-O}	Isolation capacitor				3		pF
CMTI	Common Mode Transient Immunity		CM = 1 kV, transient e = 800 V	25			kV/μs

	PARAMETERS	CONDITIONS	Min.	Тур.	Max.	Unit
	Maximum Data Rate				20	Mbps
DRIVER						•
t _{PLH} , t _{PHL}	Propagation Delay			30	60	ns
tskew	Skew (T _{PHL} -T _{PLH})	$R_L = 54 \ \Omega, C_{L1} = C_{L2} = 100 \ pF,$ Figure 11			15	ns
tr, tf	Rise/Fall Time				60	ns
RECEIVER						•
t _{PLH} , t _{PHL}	Propagation Delay	0 45 5		60	150	ns
tskew	Differential Skew (T _{PLH} - T _{PHL})	C _L = 15 pF, Figure12			20	ns
tr, tf	Bus rise/fall time			25		ns

Physical Specifications

PARAMETERS	Value	Unit
Weight	0.4(Typ.)	g

Typical Performance Curves

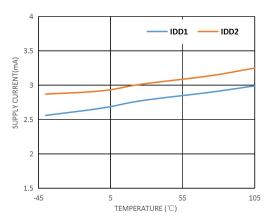


Figure 3. Unloaded Supply Current vs. Temperature

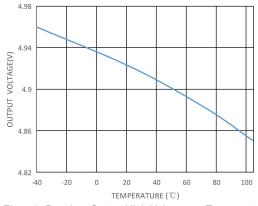


Figure 5. Receiver Output High Voltage vs. Temperature

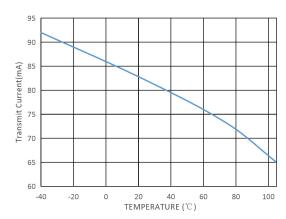


Figure 4. Transmit Current vs. Temperature, VDD1=5V, VDD2=5V

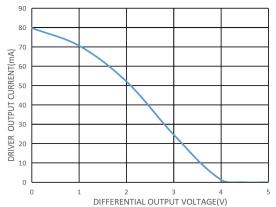


Figure 6. Driver Output Current vs. Differential Output Voltage

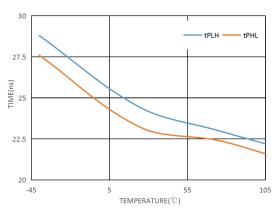


Figure 7. Driver Progation Delay vs. Temperature

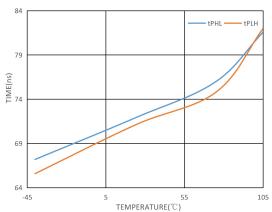


Figure 8. Receiver Progation Delay vs. Temperature

Test Circuits

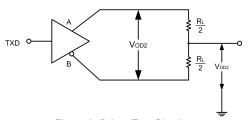


Figure 9. Driver Test Circuit

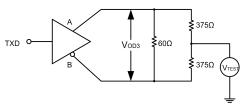
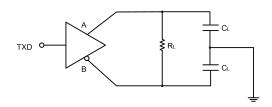


Figure 10. Driver Test Circuit, VOD With Common-Mode Loading



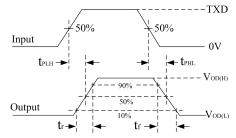
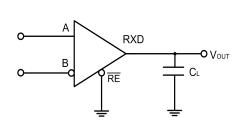


Figure 11. Drive propagation delay test circuit and wave forms



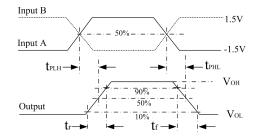


Figure 12. Receiver propagation delay test circuit and wave forms

Detailed Description

TD041S485S is an advanced RS-485 transceivers. They each contain one driver and one receiver. These devices feature a fail-safe circuitry that guarantees a high receiver output voltage when the receiver inputs are either open, shorted or when they are connected to a terminated transmission line with all drivers disabled. TD041S485S operates with a two power supply. Their logic side supports 3.3V and 5V logic level conversion. The whole machine can monitor the overall working state of the module and limit the output high current to prevent the bus from overload or short circuit causing unrecoverable damage to the transceiver.

Receiver input filter: TD041S485S receiver have an integrated input filter which enhances noise immunity of the high-speed differential signals. The receiver propagation delay increases due to this filtering.

Bus fail-safe: Ordinary RS485 bus receivers will be in an indeterminate state when -200mV< A - B <-10mV. This situation can occur whenever the data bus is not being actively driven. The advanced Fail-safe feature of the TD041S485S guarantees a high receiver output voltage if the receiver's differential inputs are either shorted, open circuit, or if they are connected to a termination resistor.

The TD041S485S receiver thresholds are very precise, and the offset between threshold voltage and ground has a margin of at least 10mV. This guarantees that the receiver output is a high voltage even the input differential is zero volts, thus maintaining compliance with the EIA/TIA-485 standard.

Load abilities on the bus (256 nodes) The standard receiver input impedance of RS-485 is $12k\Omega$ (1 unit load). A standard RS485 driver can drive at least 32 unit loads. The TD041S485S transceiver is designed to 1/8th of the standard unit load and the input impedance is higher than $96k\Omega$, hence allowing up to 256 unit loads. The TD041S485S can work combined with other standard RS485 that use the smaller amount of unit loads.

Low power shutdown mode A low-power shutdown mode is triggered by simultaneously bringing high and DE low. During shutdown mode the device supply current is 6mA typical. DE and can be directly connected and controlled by the same I/O. The devices are guaranteed not to enter shutdown mode if is high and DE is low for less than 50ns. If this state is maintain for at least 600ns, the device will shutdown reliably.

Driver output protection The device prevents excessive output current caused by fault conditions or driver short circuit. A driver current limit on the output stage provides and ensures immediate protection against short circuits over the entire common mode voltage range.

Application circuit

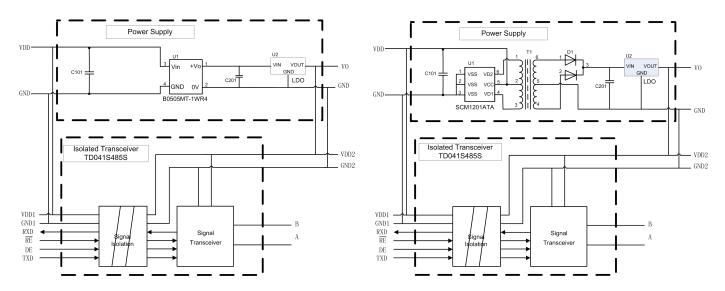


Figure 13. Receiver propagation delay test circuit and wave forms

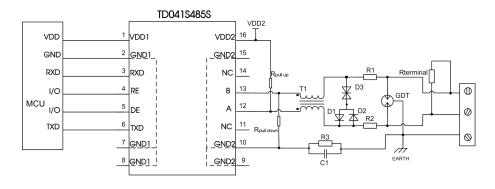


Figure 14. Port protection circuit for harsh environments

Recommended components and values:

Component	Recommended part, value	Component	Recommended part, value
R3	1ΜΩ	R1, R2	2.7Ω/2W
C1	1nF, 2kV	D1, D2	1N4007
T1	ACM2520-301-2P	D3	SMBJ8.5CA
GDT	B3D090L	R _{terminal}	120Ω

As the modules internal A / B lines come with its own ESD protection, which generally satisfy most application environments without the need for additional ESD protection devices. For harsh and noisy application environments such as motors, high voltage/current switches, lightning and similar however, we recommended that the user protects the module' s A / B lines with additional measures and external components such as TVS tube,

common mode inductors, Gas discharge tube, shielded twisted pair of wires with the same single network Earth point. Figure 14 shows our recommended circuit diagram for such type of applications with components and values given in the table above. This recommendation is for reference only and may have to be adapted accordingly with appropriate component values in order to match the actual situation and application.

Note: ①Select the R_{terminal} according to the actual application.

②When using the recommended port protection circuit, it is recommended that the communication rate be less than 10Mbps. If high-speed conditions are used, the port protection circuit will affect the bus output.

Using Suggests

- ① Hot-swap is not supported.
- ② If the external input of TXD is insufficient, the pull-up resistor should be added according to the situation.
- 3 Refer to IPC 7093 for the welding process design of this product. For detailed operation guidance, please refer to Hot Air Gun Welding Operation Instruction for DFN Package Product or Welding Operation Instruction for DFN Package Product.

Ordering Information

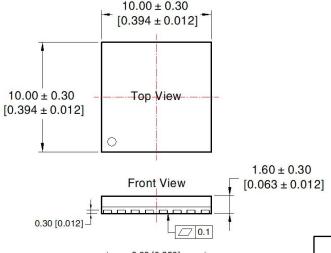
Part number	Package	Number of pins	Product Marking	Tape & Reel		
TD041S485S	DFN	16	TD041S485S	500/REEL		

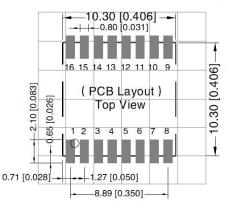
Package Information

THIRD ANGLE PROJECTION +









Note: Grid 2.54*2.54mm

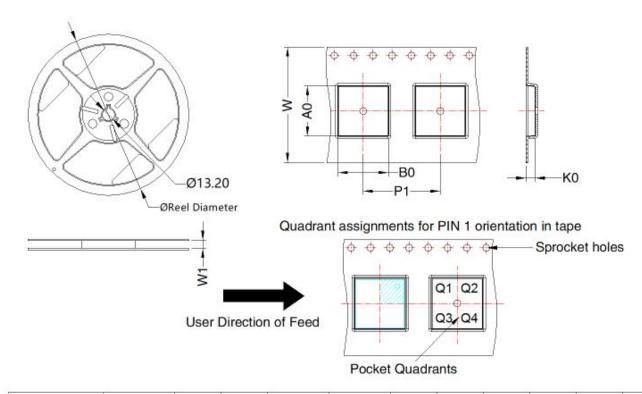
8.89 [0.350]
1 2 3 4 5 6 7 8
1 2 3 4 5 6 7 8 [240 0] 08 - Bottom View - 0.60 [0.024]
0.60 [0.024]
R0.40 [R0.016]

Pin-Out							
Pin	Mark	Pin	Mark				
1	VDD1	9	GND2				
2	GND1	10	GND2				
3	RXD	11	NC				
4	RE	12	Α				
5	DE	13	В				
6	TXD	14	NC				
7	GND1	15	GND2				
8	GND1	16	VDD2				

Note:

Unit: mm[inch]

General tolerances: $\pm 0.10[\pm 0.004]$



Device	Package Type	Pin	MPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TD041S485S	DFN 10x10	16	500	180.0	24.4	10.44	10.44	2.0	16.0	24.0	Q2

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